EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"4876588".pn.	USPAT	OR	OFF	2009/03/15 20:08
L2	27	("3686539" | "4172261" | "4319264" | "4611238" | "4829403").PN. OR ("4876588").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/03/15 20:25
L3	19	("3047780" | "3214654" | "3442012" | "3567508").PN. OR ("3686539").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/03/15 20:28
L4	24	257/E23.006	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 20:30
L5	19	257/E23.109	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 20:31
L6	1279	257/720	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 20:33
L7	2601	257/713	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 20:36
L8	2	"20060087023"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 20:42

L9	1635	257/675	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 20:49
L10	111	257/178	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 20:59
L11	3129	257/734	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 21:01
L12	1329	257/727	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 21:13
L13	3700	257/690	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 21:30
L14	93	257/118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 21:34
L15	139	257/181	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 21:41
L16	4324	361/687	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 21:43

L17	1598	361/688	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 21:44
L18	135	428/556	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 21:52
L19	1	(semiconductor or die or dice or IC or chip) and main near electrode and main near connection and lamina	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 22:07
L20	7	(semiconductor or die or dice or IC or chip) and main near electrode and connection and lamina	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 22:07
L21	542	(semiconductor or die or dice or IC or chip) and electrode and connection and lamina	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/03/15 22:07

3/15/2009 10:09:24 PM
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